

IN THE CLAIMS

1. (Canceled)

2. (currently amended) A system for processing a semiconductor device, the system comprising:
a processing chamber heated by heating elements; and
a first plate positioned within said processing chamber and defining a first internal cavity configured to receive a first gas through a first passage into said first internal cavity at a first temperature and to emit said first gas from said first internal cavity at a second temperature through a second passage; and
a second plate disposed adjacent to said first plate, said first plate and said second plate provided between said heating elements and defining a processing area therebetween, said second plate defining a second internal cavity configured to receive a second gas through a first passage into said second internal cavity at a first temperature and to emit said second gas from said second internal cavity at a second temperature through a second passage, said first emitted gas and said second emitted gas varying the temperature of said processing area.

3. (currently amended) The system of Claim 2, wherein said second passage ~~comprise~~ comprises a plurality of holes defined on a surface of said first and said second plates.

4. (previously presented) The system of Claim 2, wherein said first plate and said second plate comprise a heat source for heating said plate to a preselected temperature.

5. (previously presented) The system of Claim 2, wherein said first gas is taken from the group consisting of N₂, He, H₂, O₂, Ar and gas mixtures containing He, H₂, O₂, Ar and N₂.

6. (previously presented) The system of Claim 2, wherein said internal cavity further comprises a buffer to disperse said first gas throughout said internal cavity.

7. (canceled)

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8. (currently amended) A system for wafer processing comprising:
a chamber heated by heating elements; and
a first heatable plate and a second heatable plate positionable positioned between said heating elements within said chamber, and defining a processing area therebetween, each of said heatable plates including:

an internal cavity defining an internal wall and configured to receive a gas;
means for heating said internal wall to a preselected temperature; and
an outlet portion defining a plurality of holes for emitting said gas to said processing area;
said gas varying the temperature of said processing area.

9. (previously presented) The system of Claim 8, wherein said gas is taken from the group consisting of He, H₂, O₂, Ar, N₂ and gas mixtures containing He, H₂, O₂, Ar, and N₂.

10. (previously presented) The system of Claim 8, wherein said internal cavity further comprises a buffer to disperse said first gas throughout said internal cavity.

11.-16. (canceled)

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